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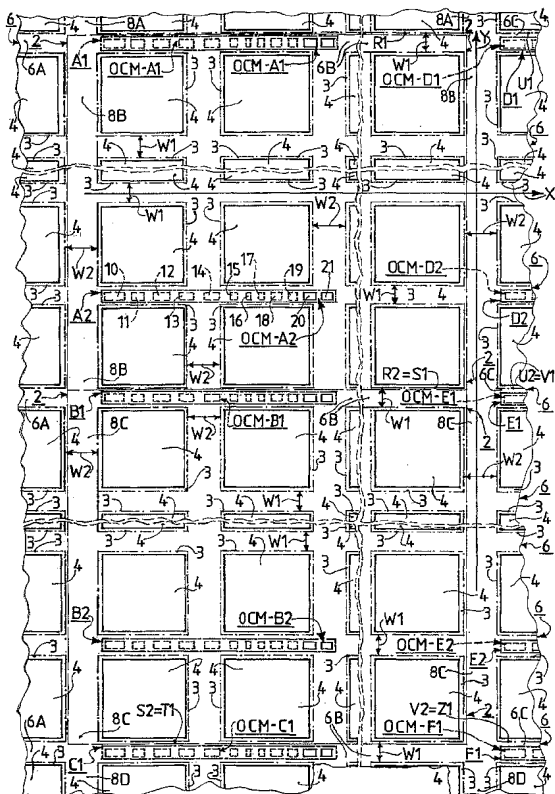
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(54) Title: WAFER WITH OPTICAL CONTROL MODULES IN DICING PATHS



(57) Abstract: In a wafer (1) with a number of exposure fields (2), each of which exposure fields (2) comprises a number of lattice fields (3) with an IC (4) located therein, two groups (5, 7) of dicing paths (6, 8) are provided and two control module fields (A1, A2, B1, B2, C1, D1, D2, E1, E2, F1) are assigned to each exposure field (2), each of which control module fields extends parallel to a first direction (X) and contains at least one optical control module (OCM-A1, OCM-A2, OCM-B1, OCM-B2, OCM-C1, OCM-D1, OCM-D2, OCM-E1, OCM-E2, OCM-F1), wherein a first control module field (OCM-A1, OCM-B1, OCM-C1, OCM-D1, OCM-E1, OCM-F1) of each exposure field (2) is located between a first edge (R1, S1, T1, U1, V1, Z1) and a row of lattice fields (3) of the exposure field (2) in question and a second control module field (OCM-A2, OCM-B2, OCM-D2, OCM-E2) is located between two rows of lattice fields (3) of the exposure field (2) in question, which are arranged adjacent to a second edge (R2, S2, T2, U2, V2), and wherein both the first control module fields (OCM-A1, OCM-B1, OCM-C1, OCM-D1, OCM-E1, OCM-F1) and the second control module fields (OCM-A2, OCM-B2, OCM-D2, OCM-E2) each lie in a first dicing path (6).



FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO,
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